XPort6191

End of Life

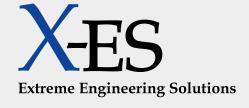Small Form Factor 64 GB Removable SATA Solid-State Drive (SSD)

Please see XPort6193

- Small Form Factor (SFF); fits within a standard 3U 0.8 in. pitch slot
- -40°C to +85°C operating temperature range
- High-reliability 100,000 life cycle connector
- Hot Swappable capabilities possible in some configurations
- Easy insertion and extraction mechanism
- 36 connector key options
- Up to 64 GB capacity
- 110 MB/s read and 90 MB/s write performance (real world)
- Higher performance possible with optimization
- Based on reliable SLC NAND flash technology
- Designed for rugged environments
- 100,000 program/erase cycles
- Global wear leveling support for added memory endurance

XPort6191

The XPort6191 has been designed from the ground up to meet today's ruggedized storage requirements. By utilizing solid-state NAND flash technology, the XPort6191 provides a high-performance, high-density, reliable removable memory solution. The XPort6191 is capable of operating within the demanding environments of MIL-STD-810F, including harsh temperatures from -40°C to +85°C as well as rigorous shock and vibration conditions.

Designed with an extremely high-reliability connector, the XPort6191 will support up to 100,000 insertions and extractions. The use of SLC NAND flash components allows the XPort6191 to support least 100,000 program erase cycles. The card also supports global wear leveling prolonging the life of the memory. The XPort6191 provides best-in-class performance, supporting up to 110 MB/s sustained read and 90 MB/s sustained write.

X-ES

Extreme Engineering Solutions

...Always Fast

Physical Characteristics

- Small Form Factor (SFF)
- Connector keying (36 options)
- 3U cPCI or 3U VPX carriers available
- 100,000 insertions and extractions

Performance

- Serial ATA (SATA) 3 Gb/s
- 110 MB/s sustained read
- 90 MB/s sustained write
- Higher performance with optimizations

Storage Characteristics

- SLC technology
- Up to 64 GB total capacity
- 100,000 program and erase cycles
- Global wear leveling support for added program and erase endurance

Environmental Requirements

- Tested to MIL-STD-810F requirements
- Supported ruggedization levels (see chart below): 1, 3, 5

Power Requirements

- 2 W maximum, 1 W typical

Ruggedization Level	Level 1	Level 3	Level 5
Cooling Method	Standard Air-Cooled	Rugged Air-Cooled	Conduction-Cooled
Operating Temperature	0 to +55°C ambient (300 LFM)	-40 to +70°C (600 LFM)	-40 to +85°C (board rail surface)
Storage Temperature	-40 to +85°C ambient	-55 to +105°C ambient	-55 to +105°C (maximum)
Vibration	0.002 g²/Hz (maximum), 5 to 2000 Hz	0.04 g²/Hz (maximum), 5 to 2000 Hz	0.1 g²/Hz (maximum), 5 to 2000 Hz
Shock	20 g, 11 ms sawtooth	30 g, 11 ms sawtooth	40 g, 11 ms sawtooth
Humidity	0% to 95% non-condensing	0% to 95% non-condensing	0% to 95% non-condensing